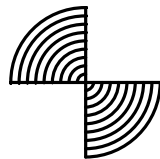
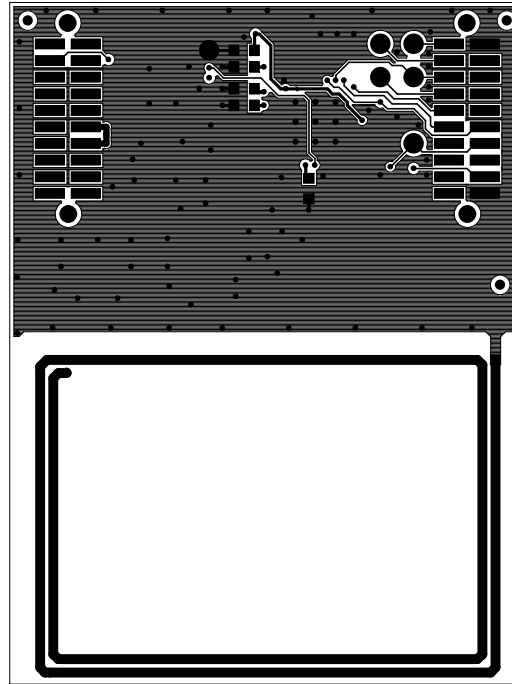
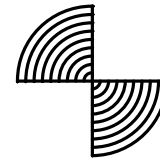
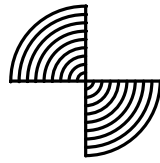
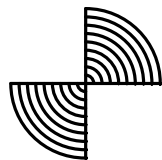
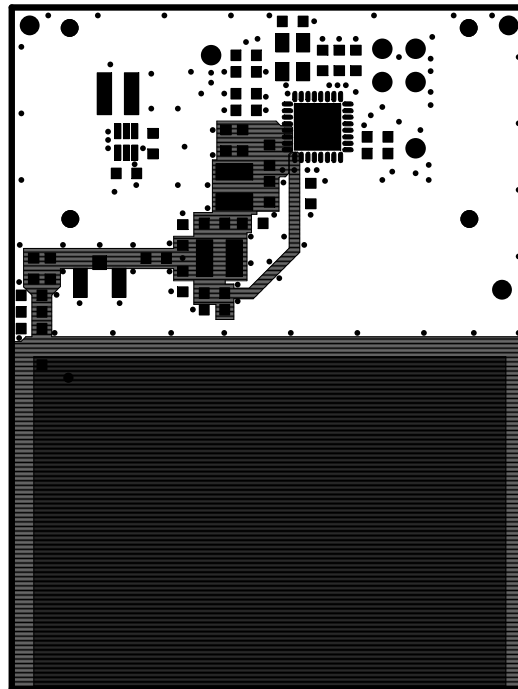
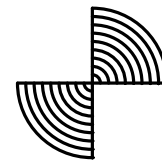
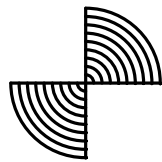


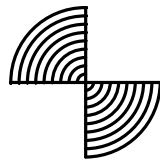
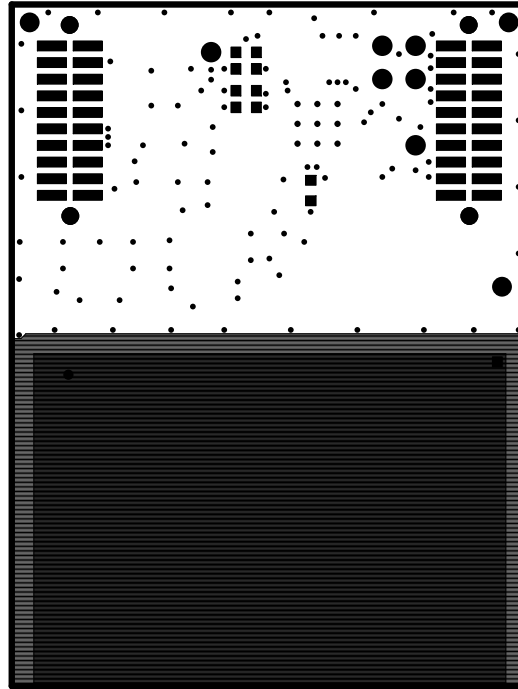
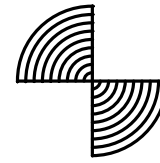
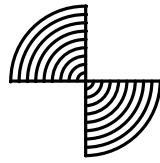
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| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | | |
| BOARD NAME: | | | DESCRIPTION: | | | | | | | | | |
| TRF7970ATB | | | LAYER 1 - PRIMARY SIDE | | | | | | | | | |
| TI TICKET NO: | | REV: | DATE: | PROJECT#: | | SH: | OF: | | | | | |
| | | D | 02/06/2013 | RFID | | 1 | 8 | | | | | |



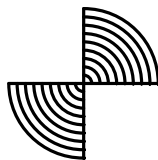
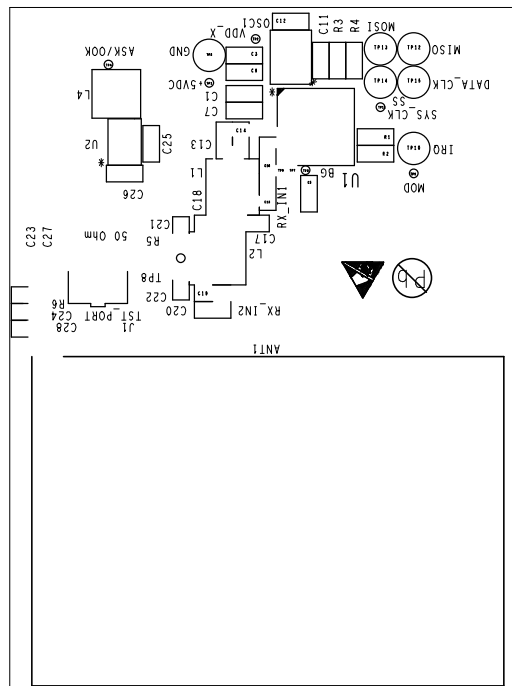
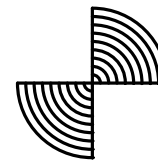
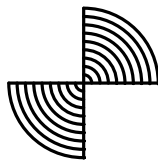
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| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | LAYER 2 - SECONDARY SIDE | | | | | | | |
| TI TICKET NO: | | REV: | DATE: | | PROJECT#: | | SH: | OF: | | | |
| | | D | 02/06/2013 | | RFID | | 2 | 8 | | | |



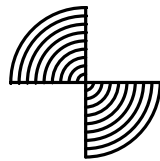
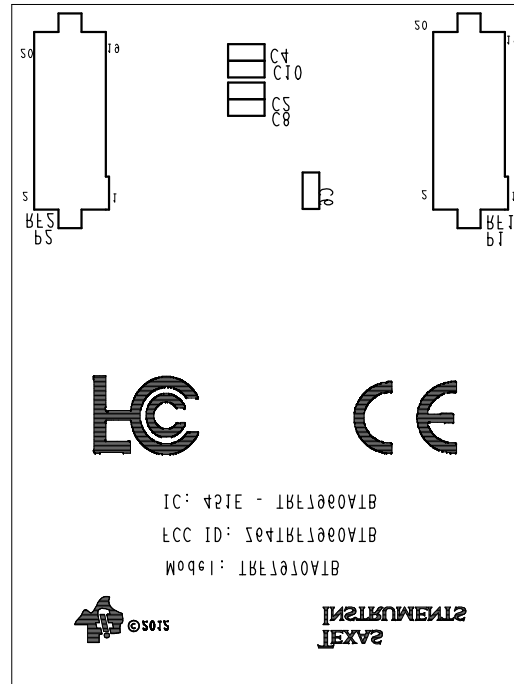
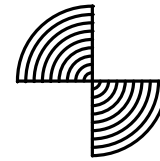
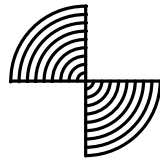
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| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | SOLDERMASK - PRIMARY SIDE | | | | | | | |
| TI TICKET NO: | | REV: | DATE: | | PROJECT#: | | SH: | OF: | | | |
| | | D | 02/06/2013 | | RFID | | 3 | 8 | | | |



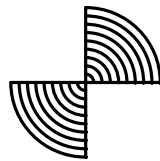
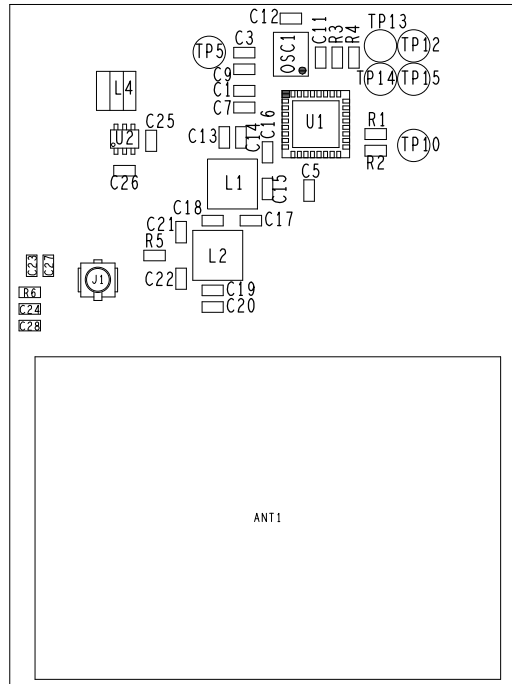
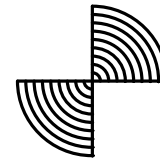
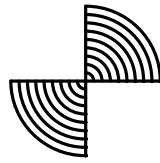
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| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | SOLDERMASK - SECONDARY SIDE | | | | | | | |
| TI TICKET NO: | | | REV: | DATE: | | PROJECT#: | | SH: | OF: | | |
| | | | D | 02/06/2013 | | RFID | | 4 | 8 | | |



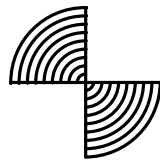
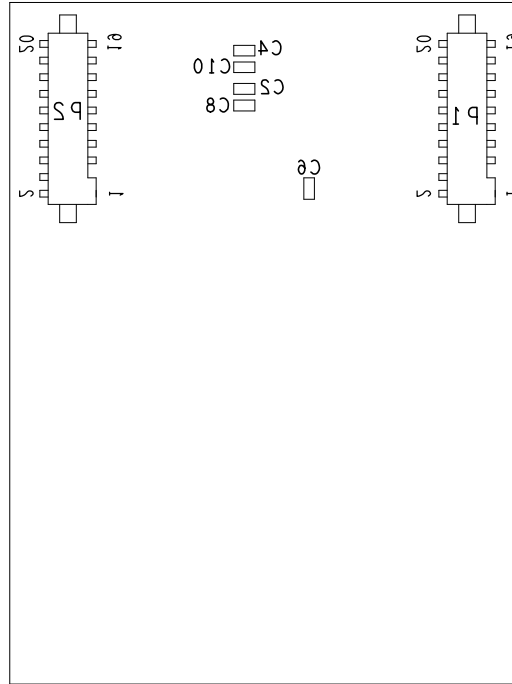
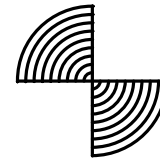
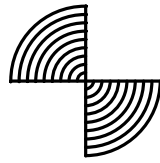
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|----------------|--|------|------------|--|-------------------|--|--|-----|--|---------------------------|--|--|--|--|
| CUSTOMER NAME: | | | | | TEXAS INSTRUMENTS | | | | | | | | | |
| BOARD NAME: | | | TRF7970ATB | | DESCRIPTION: | | | | | SILKSCREEN - PRIMARY SIDE | | | | |
| TI TICKET NO: | | REV: | DATE: | | PROJECT#: | | | SH: | | OF: | | | | |
| | | D | 02/06/2013 | | RFID | | | 5 | | 8 | | | | |



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|----------------|--|------|------------|-----------------------------|--|-------------------|-----|--|--|--|--|
| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | SILKSCREEN - SECONDARY SIDE | | | | | | | |
| TI TICKET NO: | | REV: | DATE: | PROJECT#: | | SH: | OF: | | | | |
| | | D | 02/06/2013 | RFID | | 6 | 8 | | | | |



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|----------------|--|--|------|-------------------------|-----------|-------------------|--|-----|-----|--|--|
| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | ASSEMBLY - PRIMARY SIDE | | | | | | | |
| TI TICKET NO: | | | REV: | DATE: | PROJECT#: | | | SH: | OF: | | |
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| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | ASSEMBLY - SECONDARY SIDE | | | | | | | |
| TI TICKET NO: | | | REV: | DATE: | PROJECT#: | | | SH: | OF: | | |
| | | | D | 02/06/2013 | RFID | | | 2 | 2 | | |

FAB NOTES:

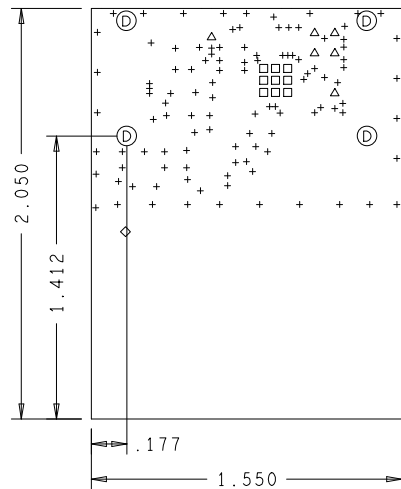
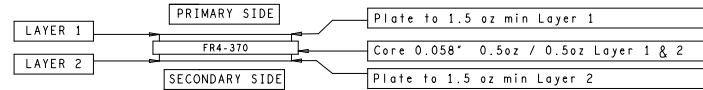
1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg / 340 Td ISOLA FR-370HR OR EQUIVALENT, RoSH COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoSH CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
5. OVERALL BOARD THICKNESS TO BE .062 +/- .005". AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
6. MAX. WARP & TWIST TO BE .0075 PER INCH.
7. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
8. 30 MIL TRACES ON LAYER 1 ARE 50 OHMS +/- 10%. THEY ARE REFERENCE TO LAYER 1 GROUND WITH SOLDERMASK CLEAR AWAY.

PROCESS NOTES:

1. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
2. PLATE ALL EXPOSED AREAS WITH ELECTROLESS NICKEL IMMERSION GOLD. NICKEL: 100 MICRO-INCHES MIN. GOLD: 2-8 MICROINCHES MIN.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY NON-CONDUCTIVE LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
5. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

LAYER STACK UP:

LAYER 1 - PRIMARY SIDE
LAYER 2 - SECONDARY SIDE

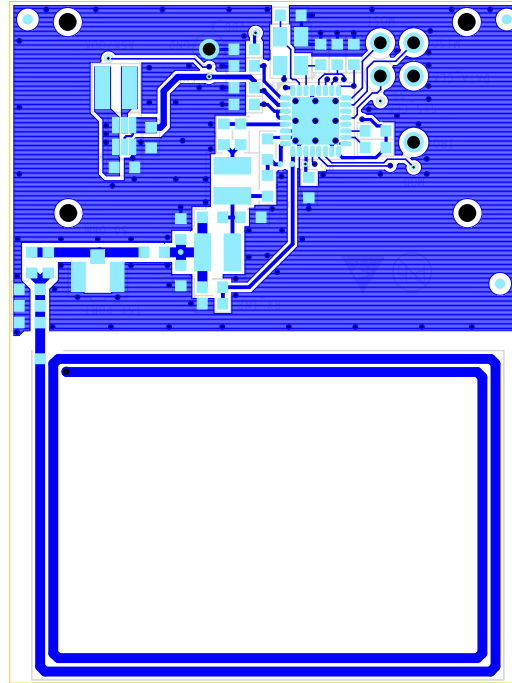


VIEWED FROM PRIMARY SIDE

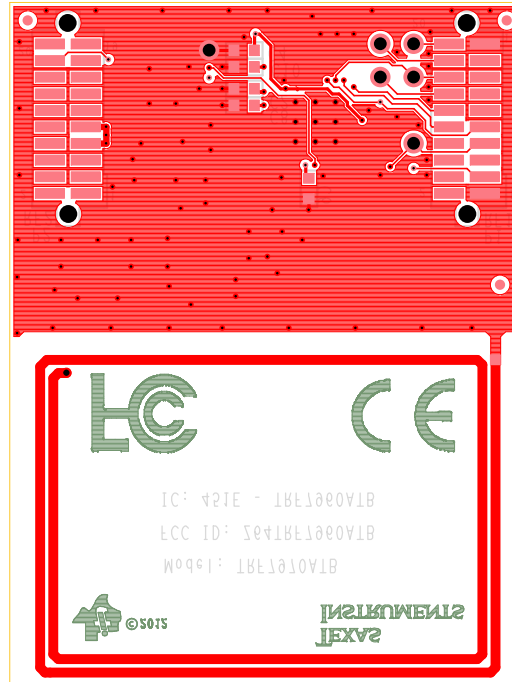
DRILL CHART: TOP to BOTTOM

| ALL UNITS ARE IN MILS | | | | |
|-----------------------|------|-----------|------------|-----|
| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
| + | 8.0 | +3.0/-3.0 | PLATED | 109 |
| □ | 12.0 | +3.0/-3.0 | PLATED | 9 |
| ◇ | 20.0 | +3.0/-3.0 | PLATED | 1 |
| △ | 38.0 | +3.0/-3.0 | PLATED | 6 |
| Ⓚ | 53.0 | +2.0/-2.0 | NON-PLATED | 4 |

| | | | | | |
|----------------------------------|--------|------------------|----------------------------------|-------|-------|
| CUSTOMER NAME: TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: TRF7970ATB | | | DESCRIPTION: FABRICATION DRAWING | | |
| TI TICKET NO: | REV: D | DATE: 02/06/2013 | PROJECT#: RFID | SH: 1 | OF: 1 |



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|----------------|--|------|------------|-----------|--|-------------------|-----|--|---------------------------|--|--|
| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | TRF7970ATB | | | DESCRIPTION: | | | BAYERGREENPRIMARYASIDEIDE | | |
| TI TICKET NO: | | REV: | DATE: | PROJECT#: | | SH: | OF: | | | | |
| | | D | 02/06/2013 | RFID | | 1 | 8 | | | | |



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| CUSTOMER NAME: | | | | | | TEXAS INSTRUMENTS | | | | | |
| BOARD NAME: | | | | DESCRIPTION: | | | | | | | |
| TRF7970ATB | | | | BAYERC2EENSECONDARYASIDEIDE | | | | | | | |
| TI TICKET NO: | | REV: | DATE: | PROJECT#: | | SH: | OF: | | | | |
| | | D | 02/06/2013 | RFID | | 2 | 8 | | | | |

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